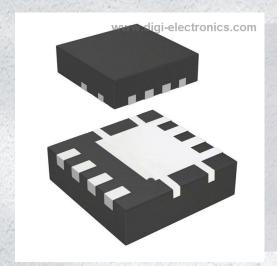


DMT3004LFG-13 Datasheet



https://www.DiGi-Electronics.com

DiGi Electronics Part Number DMT3004LFG-13-DG

Manufacturer Diodes Incorporated

Manufacturer Product Number DMT3004LFG-13

Description MOSFET NCH 30V 10.4A POWERDI

Detailed Description N-Channel 30 V 10.4A (Ta), 25A (Tc) 2.1W (Ta), 42W

(Tc) Surface Mount POWERDI3333-8



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

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Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
DMT3004LFG-13	Diodes Incorporated
Series:	Product Status:
	Active
FET Type:	Technology:
N-Channel	MOSFET (Metal Oxide)
Drain to Source Voltage (Vdss):	Current - Continuous Drain (Id) @ 25°C:
30 V	10.4A (Ta), 25A (Tc)
Drive Voltage (Max Rds On, Min Rds On):	Rds On (Max) @ Id, Vgs:
4.5V, 10V	4.5mOhm @ 20A, 10V
Vgs(th) (Max) @ Id:	Gate Charge (Qg) (Max) @ Vgs:
3V @ 250μA	44 nC @ 10 V
Vgs (Max):	Input Capacitance (Ciss) (Max) @ Vds:
+20V, -16V	2370 pF @ 15 V
FET Feature:	Power Dissipation (Max):
	2.1W (Ta), 42W (Tc)
Operating Temperature:	Grade:
-55°C ~ 150°C (TJ)	Automotive
Qualification:	Mounting Type:
AEC-Q101	Surface Mount
Supplier Device Package:	Package / Case:
PowerDI3333-8	8-PowerVDFN
Base Product Number:	
DMT3004	

Environmental & Export classification

8541.29.0095

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	





N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} max	I _D max T _C = +25°C (Note 9)
30V	$4.5 \text{m}\Omega$ @ $V_{GS} = 10V$	25A
30 V	$7.0 \text{m}\Omega$ @ $V_{GS} = 4.5 \text{V}$	25A

Description and Applications

This MOSFET has been designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

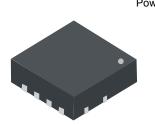
- Backlighting
- Power Management Functions
- DC-DC Converters

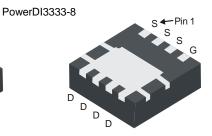
Features and Benefits

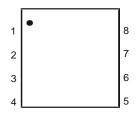
- Low R_{DS(ON)} Ensures on State Losses Are Minimized
- Excellent Q_{gd x} R_{DS(ON)} Product (FOM)
- Advanced Technology for DC/DC Converters
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- Occupies Just 33% of The Board Area Occupied by SO-8 Enabling Smaller End Product
- 100% UIS (Avalanche) Rated
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

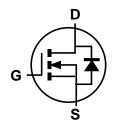
Mechanical Data

- Case: PowerDI[®]3333-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.072 grams (Approximate)









Top View

Bottom View

Top View Equivalent Circuit

Ordering Information (Note 4)

Part Number	Case	Packaging
DMT3004LFG-7	PowerDI3333-8	2,000/Tape & Reel
DMT3004LFG-13	PowerDI3333-8	3,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



SG3 = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 18 = 2018) WW = Week Code (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V _{DSS}	30	V
Gate-Source Voltage		V _{GSS}	+20 -16	V
Continuous Drain Current (Notes 6 & 9) V _{GS} = 10V	$T_{C} = +25^{\circ}C$ $T_{C} = +70^{\circ}C$	I _D	25 25	А
Continuous Drain Current (Note 5) V _{GS} = 10V	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	10.4 8.3	А
Maximum Continuous Body Diode Forward Current (Note 5)		Is	3	Α
Pulsed Drain Current (10µs pulse, Duty Cycle = 1%)		I _{DM}	95	А
Avalanche Current, L=0.3mH		I _{AS}	27	А
Avalanche Energy, L=0.3mH		E _{AS}	110	mJ

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 6)	T _C = +25°C	P_{D}	42	W
Thermal Resistance, Junction to Case (Note 6)		$R_{ heta JC}$	3	°C/W
Total Power Dissipation (Note 5)	T _A = +25°C	P _D	2.1	W
Thermal Resistance, Junction to Ambient (Note 5)		$R_{ heta JA}$	60	°C/W
Operating and Storage Temperature Range		$T_{J_1}T_{STG}$	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	30	-	-	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	-	-	1	μΑ	$V_{DS} = 24V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	-	-	100 -100	nA	V _{GS} = +20V, V _{DS} = 0V V _{GS} = -16V, V _{DS} = 0V	
ON CHARACTERISTICS (Note 7)	•	I.			l .		
Gate Threshold Voltage	V _{GS(TH)}	1	-	3	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance		-	3.5	4.5		$V_{GS} = 10V, I_D = 20A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	-	5	7.0	mΩ	$V_{GS} = 4.5V, I_D = 7A$	
Diode Forward Voltage	V_{SD}	-	0.7	1	V	$V_{GS} = 0V$, $I_S = 1A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	-	2370	-		V _{DS} = 15V, V _{GS} = 0V, f = 1MHz	
Output Capacitance	Coss	-	1360	-	pF		
Reverse Transfer Capacitance	C _{rss}	-	240	-			
Gate Resistance	Rg	-	0.6	-	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Qg	-	20	-			
Total Gate Charge (V _{GS} = 10V)	Qq	-	44	-	nC	\\\\ 45\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	
Gate-Source Charge	Q _{gs}	-	7	-	iiC	$V_{DS} = 15V, I_{D} = 20A$	
Gate-Drain Charge	Q _{qd}	-	8	-			
Turn-On Delay Time	t _{D(ON)}	-	6.2	-			
Turn-On Rise Time	t _R	-	4.3	-		$V_{DD} = 15V, V_{GS} = 10V,$ $R_L = 0.75\Omega, R_G = 3\Omega, I_D = 20A$	
Turn-Off Delay Time	t _{D(OFF)}	-	21	-	ns		
Turn-Off Fall Time	t _F	-	8	-			
Body Diode Reverse Recovery Time	t _{RR}	-	25	-	ns	1 45A 31/34 500A/35	
Body Diode Reverse Recovery Charge	Q _{RR}	-	37	-	nC	I _F = 15A, di/dt = 500A/μs	

Notes:

- 5. $R_{\theta JA}$ is determined with the device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.
- Willie R_{0JA} is determined by the user's board design.

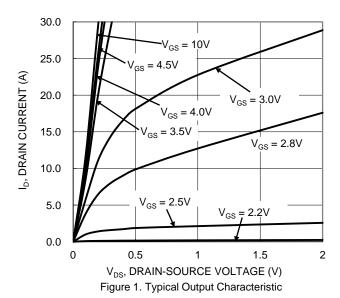
 6. Thermal resistance from junction to soldering point (on the exposed drain pad).

 7. Short duration pulse test used to minimize self-heating effect.

 8. Guaranteed by design. Not subject to product testing.

 9. Package limited.





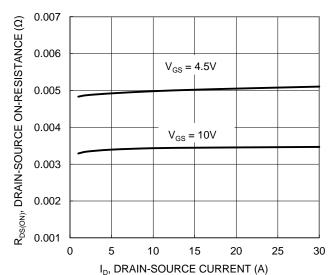


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

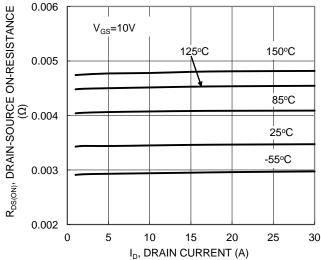


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

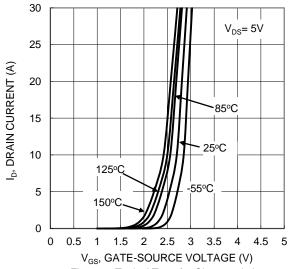


Figure 2. Typical Transfer Characteristic

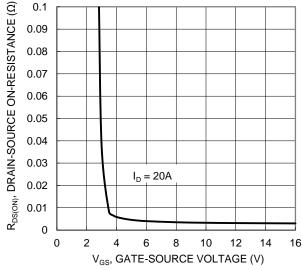
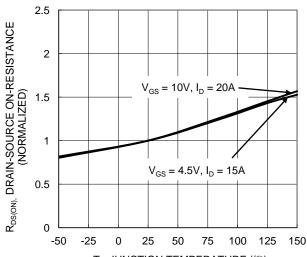


Figure 4. Typical Transfer Characteristic



T_J, JUNCTION TEMPERATURE (°C) Figure 6. On-Resistance Variation with Junction Temperature

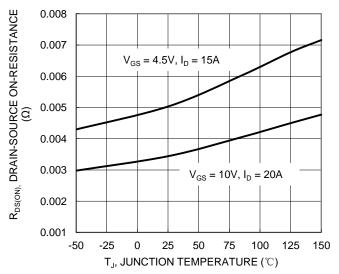
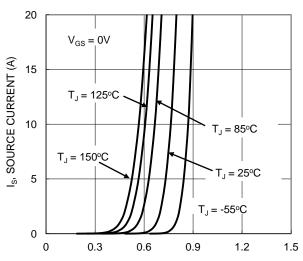


Figure 7. On-Resistance Variation with Junction Temperature



V_{SD}, SOURCE-DRAIN VOLTAGE (V) Figure 9. Diode Forward Voltage vs. Current

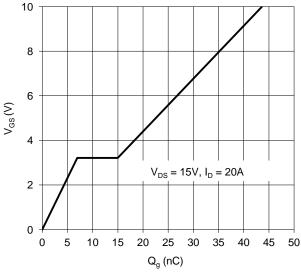


Figure 11. Gate Charge

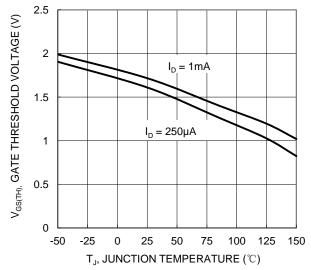
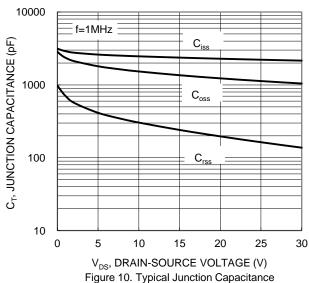


Figure 8. Gate Threshold Variation vs. Junction Temperature



1000 $R_{DS(ON)}$ Limited 100 ID, DRAIN CURRENT (A) 10 1 T_{J(Max)}=150℃ T₄=25°C 0.1 =10s Single Pulse DC DUT on 1*MRP board V_{GS}=10V 0.01 0.01 100 V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 12. SOA, Safe Operation Area



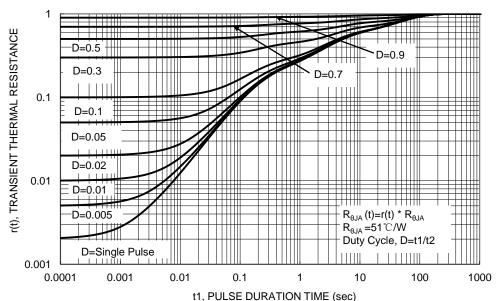


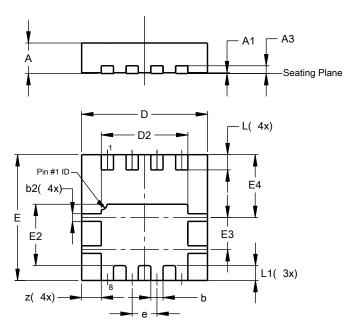
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8

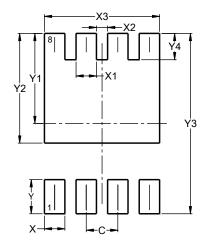


PowerDI3333-8					
Dim	Min	Max	Тур		
Α	0.75	0.85	0.80		
A1	0.00	0.05	0.02		
A3	_	_	0.203		
b	0.27	0.37	0.32		
b2	0.15	0.25	0.20		
D	3.25	3.35	3.30		
D2	2.22	2.32	2.27		
Е	3.25	3.35	3.30		
E2	1.56	1.66	1.61		
E3	0.79	0.89	0.84		
E4	1.60	1.70	1.65		
е	-	-	0.65		
L	0.35	0.45	0.40		
L1	_	_	0.39		
Z	_	_	0.515		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8



Dimensions	Value (in mm)
С	0.650
Х	0.420
X1	0.420
X2	0.230
Х3	2.370
Υ	0.700
Y1	1.850
Y2	2.250
Y3	3.700
Y4	0.540



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